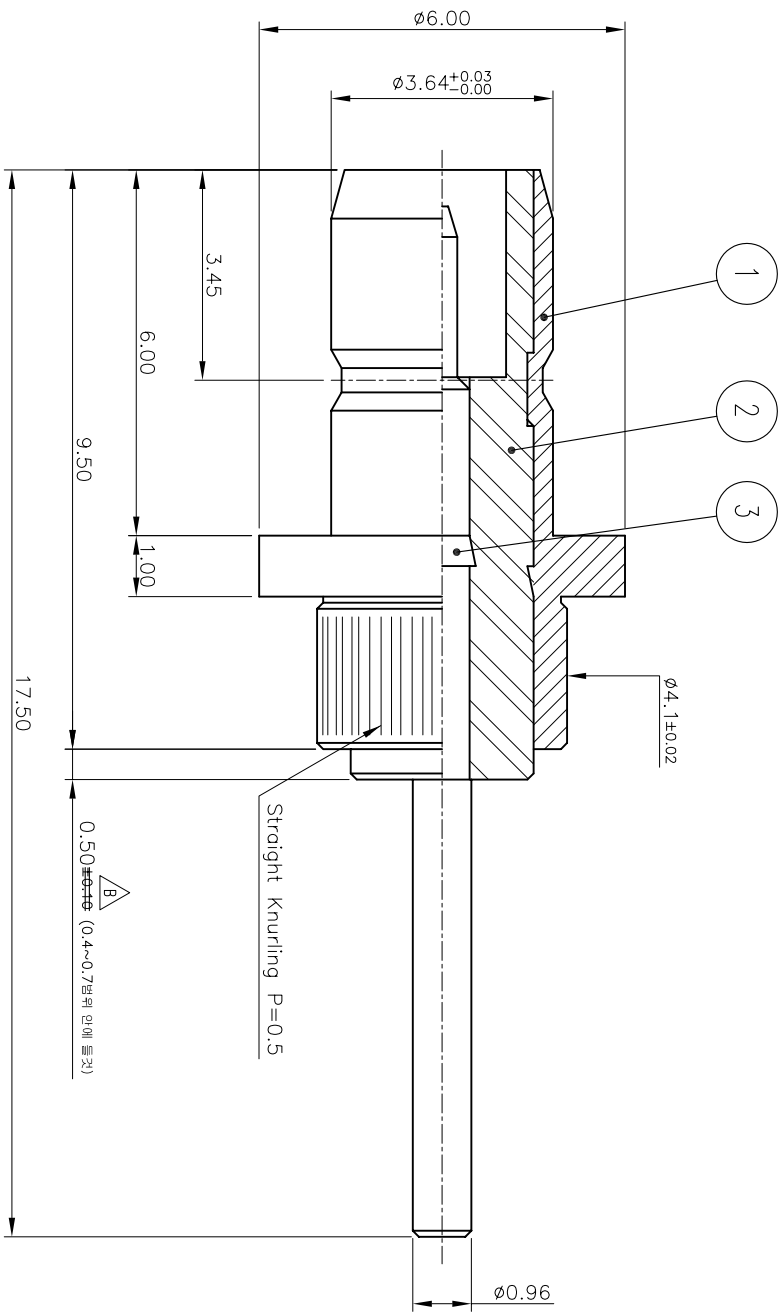


REVISION		
REV	DESCRIPTION	DATE
R	최초 개정	2007. 08. 08.
A	신뢰성 향상[설비200902-0001] 핀 벤딩 시 TEF 이물 방지 누시바를 추가	2009. 02. 02.
B	신뢰성 향상[설비200902-0015] BODY 누시바를 추가로 인한 TEF LON 결이 및 공차변경	2009. 02. 19.



$\sqrt{B}$	3	INSULATOR	1	TEFLON	White	DIN01519-N/1 DIN01061-N/1 (#3158)
$\sqrt{B}$	2	CONTACT	1	MBSBD	Gold ($0.0\mu m$)	DCT01144-5/1 (E3177)
$\sqrt{A}$	1	BODY	1	MBSBD	Nickel Plate	DBD01501-5/1 (D3183)
NO.		DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE		Decimal	DATE	 KOMTECH RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
Angle		± 0.1	2009. 02. 19.			
MATERIAL		$\pm 1^\circ$	APPROVED BY	TITLE SMB50-J-BR		
			S.J.YOUN			
FINISH			CHECKED BY	DWG NO. CN00818-7/1 (K315-512-001)		
			I.C.KIM			
			DRAWN BY	REVISION B		
			E.H.KIM			
			SCALE	SHEET 1 of 1		
			8/1 mm			